

**IN THE CLAIMS:**

Claims 1-10 (canceled)

Claim 11 (currently amended) A semiconductor device, comprising:

a semiconductor chip having a top surface, said semiconductor chip carrying a first electrode;

a circuit substrate attached to a top surface of said semiconductor chip, said circuit substrate carrying thereon a predetermined conductor pattern including a second electrode and a third electrode;

a solder resist layer provided on said circuit substrate;

a resin layer intervening between said top surface of said semiconductor chip and said circuit substrate;

a spherical electrode formed in an opening in said solder resist layer on said circuit substrate in correspondence to said third electrode;

a bonding wire electrically interconnecting said second electrode of said predetermined conductor pattern on said circuit substrate and said first electrode on said semiconductor chip; and

a resin potting encapsulating said bonding wire including said first and second electrodes, said chip and said resin potting being defined by a flat common edge surface when viewed in a direction substantially perpendicular to a principal surface of said substrate,

wherein said resin layer has a composition substantially identical with a composition of said resin potting.

Claim 12 (original) A semiconductor device as claimed in claim 11, wherein said resin layer is an adhesive layer.

Claim 13 (canceled)

Claim 14 (original) A semiconductor device as claimed in claim 11, wherein said circuit substrate is formed of a glass epoxy.

Claim 15 (original) A semiconductor device as claimed in claim 11, wherein said circuit substrate is formed of a polyimide film.

Claim 16 (currently amended) A semiconductor device, comprising:

a semiconductor chip having a top surface, said semiconductor chip carrying a first electrode;

a circuit substrate provided on a top surface of said semiconductor chip with a separation therefrom, said circuit substrate carrying thereon a predetermined conductor pattern including a second electrode and a third electrode;

a spherical electrode provided on said circuit substrate in correspondence to said third

electrode;

a bonding wire electrically interconnecting said second electrode of said predetermined conductor pattern on said circuit substrate and said first electrode on said semiconductor chip;

a resin potting encapsulating said bonding wire including said first and second electrodes, said resin potting filling a space between said semiconductor chip and said circuit substrate; and

a resin side wall cover covering a side wall of said circuit substrate, said resin sidewall being defined by a flat sidewall surface;

said chip having a side wall substantially flush to ~~an outer surface~~ said flat sidewall surface of said resin side wall cover, said side wall of said chip being substantially perpendicular to a principal surface of said chip.

Claim 17 (original) A semiconductor device as claimed in claim 16, wherein said resin potting and said resin side wall cover have a substantially identical composition.